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United States Patent [19] Orth

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[54] **PROCESS AND SYSTEM FOR FLATTENING SECONDARY EDGE BEADS ON RESIST COATED WAFERS**

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Related U.S. Application Data

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[51] **Int. Cl.⁶** **G03D 5/00**

[52] **U.S. Cl.** **396/611**; 396/627; 427/231; 427/235; 427/240; 134/157

[58] **Field of Search** 396/611, 604, 396/627; 118/52; 427/240, 273, 231, 235; 134/157, 153, 198; 355/53, 43, 45; 430/311, 331

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[57] ABSTRACT

A method and system of flattening resist mounds formed during a wet edgebead operation. The wet edgebead operation is used to remove edgebeads formed when a resist material is deposited on a semiconductor wafer. Solvent is introduced to the semiconductor wafer at the area containing the resist mounds to soften them, and the semiconductor wafer is spun at a high speed to flatten the mounds.

21 Claims, 7 Drawing Sheets

